

TECHNICAL DATA SHEET

INSTALLING PARQUET AND FLOORING ON CEMENT-BONDED PARTICLE BOARD (UG 4)

WHAT IS CEMENT-BONDED PARTICLE BOARD?

This type of prefab panel is a wood-based panel that competes with conventional chipboard or other prefab panels.

3-layer structure of coarse and fine chips. The fine chips form the outer layers and the coarse chips the middle layer. During production, these chips are pressed together with cement, water and mineralisation materials to form a board of a nominal thickness. As an installation panel, it is sanded on both sides, trimmed and provided with a tongue and groove on 4 sides.

Cement-bonded particle board is used in various versions in the construction sector or also as installation panels in dry mortarless construction.

In the bonding process, cement is used instead of the usual binder (phenolic resin) for chipboard; the binder therefore does not constitute a source of formaldehyde emissions.

Due to their high density, the installation panels have a high deadweight.

The surface structure of the cement-bonded installation panels is very fine-grained, similar to that of a levelling compound.

NOTE WHEN INSTALLING CEMENT-BONDED PARTICLE BOARD:

To accommodate parquet, it is recommended that the cement-bonded particle board is full-surface bonded or screwed together

firmly.

In floating installation of the cement-bonded particle board according to the manufacturer's instructions, and when stuck to wood types (e.g. maple, beech), and/or to solid wood parquet dimensions (10 mm solid parquet, 22 mm strip parquet) which are sensitive to swelling pressure, it should be noted that if high swelling pressure (e.g. high air humidity) occurs, strong tension may build up in the parquet top surface which can result in the floor construction welling up.

INSTALLING PARQUET AND FLOORING ON CEMENT-BONDED PARTICLE BOARD:

Cement-bonded particle board is suitable for supporting resilient and textile floor coverings and parquet.

A surface covered with installation panels constitutes a relatively even and level substrate. The risk of cavities forming during parquet installation is therefore generally much lower than with conventional screed installation.

Almost all types of floor coverings and parquet can be installed on cement-bonded particle boards, using adhesives from the STAUF range, in accordance with the table below. STAUF adhesive application tables should be taken into account when selecting appropriate types of adhesive.

APPLICABLE PRIMERS FOR ADHESIVES/LEVELLING COMPOUNDS ON CEMENT-BONDED PARTICLE BOARD

	STAUF flooring adhesives	STAUF dispersion-based adhesive for wood flooring	STAUF Reactive resin adhesives*	STAUF XP 40 + reinforcement fibres
STAUF VDP 130	✓	✓	✓ ¹⁾	✓
STAUF VDP 160			✓ ¹⁾	✓
STAUF D 54	✓	✓		✓
STAUF VPU 155 S			✓ ¹⁾	✓ ²⁾
STAUF WEP 180			✓ ¹⁾	✓ ²⁾
STAUF VEP 195			✓ ¹⁾	✓ ²⁾

1) usually not necessary

2) in combination with levelling compounds + STAUF quartz sand.

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APPLICABLE ADHESIVE SYSTEMS

	STAUF flooring adhesives	STAUF Dispersion-based wood flooring adhesives	STAUF reactive resin adhesives	Substrate preparation
Textile floorings	✓			Clean the substrate well and, if necessary, prime and fill according to its condition and requirements.
Resilient flooring	✓			
Linoleum	✓			
Laminate flooring (full-surface bonding)			✓	
Solid wood flooring		✓	✓	
Multi-layer parquet		✓	✓	
Wood block	Bonding in general not possible, please contact us.			

The information provided above corresponds to the current state of the art. The information is purely indicative and non-binding, since we have no control over the laying process and because the actual laying conditions on site vary. Therefore no claims can be made based on this information. The same is true for the commercial and technical advisory services that are provided without obligation and free of charge. We therefore recommend carrying out sufficient testing of your own in order to determine whether the result is suitable for the intended purpose.